

# Single Board Computer



SBC-C43

SBC with NXP i.MX 8 Applications Processors in 3.5" form factor

Industrial ARM solution for IoT edge computing applications



DEVELOPMENT

SAMPLING

PRODUCTION

## HIGHLIGHTS

CPU  
NXP i.MX 8 Family

CONNECTIVITY  
2x Gigabit Ethernet interfaces

GRAPHICS  
2x Graphics accelerators Vivante GC7000 / XVSX or GC7000Lit/XVSX (QuadPlus and Quad)

MEMORY  
Soldered down LPDDR4

Available in Industrial Temperature Range



Wind River Partner Program  
PLATINUM



## MAIN FIELDS OF APPLICATION



Biomedical/  
Medical devices



Digital Signage -  
Infotainment



Edge Computing



Industrial  
Automation and  
Control



Internet of  
Things



Smart Vision



Vending

## FEATURES

	NXP i.MX 8 Family: <b>i.MX 8QuadMax:</b> 2x ARM Cortex®-A72 + 4x ARM® Cortex®-A53 + 2x Cortex®-M4F <b>i.MX 8QuadPlus:</b> 1x ARM Cortex®-A72 + 4x ARM® Cortex®-A53 + 2x Cortex®-M4F <b>i.MX 8Quad:</b> 4x ARM® Cortex®-A53 + 2x Cortex®-M4F		1 x USB 3.0 Host port on Type-A socket 1x USB 2.0 OTG port on micro-AB socket 1x USB 2.0 Host port on external Type-A socket 1x USB 2.0 Host port on internal connector 2 x USB 2.0 ports available on M.2 Key B and Key E slots
	8		2x PCI-e x1 ports, available on M.2 Socket 1 Key E and on M.2 Socket 2 Key B (pin shared with SATA interface) Slots
	Soldered down LPDDR4 memory, 64-bit interface, 1600MHz. Base configuration 2GB, up-scalable to 4GB, 6GB, 8GB		I2S Audio Codec Mic In and Line Out interfaces, available on a single combo TRRS connector
	2x Graphics accelerators Vivante GC7000 / XVSX or GC7000Lit/XVSX (QuadPlus and Quad) 1x embedded VPU, supporting H.265 (4K30) and H.264 (1080p60) decoding and H.264 (1080p30) encoding Supports 4 independent video outputs (total combined resolution 4K)		1x UART (RS-232 level) 1x UART RS-485/RS-422 configurable 1x UART TTL level 3x CAN interfaces
	OUTPUTS: HDMI 2.0a Tx interface Optional eDP 1.4 interface Single/Dual-Channel 18-/24- bit LVDS interface INPUTS: HDMI 2.0a Rx interface 2x 4-lanes MIPI-CSI Camera interfaces		4x Analog Inputs 6x GPIOs SPI interface I2C interface Embedded additional RTC circuitry for lowest power consumption SIM dedicated slot + programmable electronic SIM on-board
	HDMI, eDP: Up to UltraHD (4K) LVDS: up to 1080p		+12V <sub>DC</sub> ± 10%
	eMMC 5.1 Drive soldered on-board, up to 32GB 1x S-ATA interface available on M.2 Socket 2 Key B Slot (interface shared with PCI-e x1) microSD Card Slot 4MB QuadSPI Flash NAND (boot device only)		Wind River Linux Yocto Android
	2x Gigabit Ethernet interfaces Combo WiFi 802.11 a/b/g/n/ac + BT LE 4.2 module with ceramic SMT antennas on-board M.2 Socket 2 Key B Slot for M.2 Modems M.2 Socket1 Key E Slot for WiFi + BT external modules		0°C ÷ +60°C (Commercial version) -40°C ÷ +85°C (Industrial version)
			146 x 102 mm (5,75" x 4,02")

\* Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.



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## BLOCK DIAGRAM

